

ABSTRACT

DICING/DIE BONDING SHEET

The present invention provides a dicing/die bonding sheet which can be used as a dicing tape during dicing, enables ready separation of the semiconductor element and the adhesive layer from the pressure-sensitive adhesive layer during pickup, and in which the adhesive layer has satisfactory adhesiveness as a die bonding material. A dicing/die bonding sheet in which the pressure-sensitive adhesive layer comprises a compound (A), containing intramolecular, radiation curable carbon-carbon double bonds with an iodine value of 0.5 to 20, and at least one compound (B) selected from a group consisting of polyisocyanates, melamine-formaldehyde resins, and epoxy resins, and the adhesive layer comprises an epoxy resin (a), a phenolic resin (b) with a hydroxyl equivalent of at least 150 g/eq., an epoxy group-containing acrylic copolymer (c), comprising from 0.5 to 6% by weight of glycidyl acrylate or glycidyl methacrylate, and with a weight average molecular weight of at least 100,000, a filler (d), and a curing accelerator (e).

Figure 1